

/ Absolute Maximum Ratings($T_a=25^\circ\text{C}$)

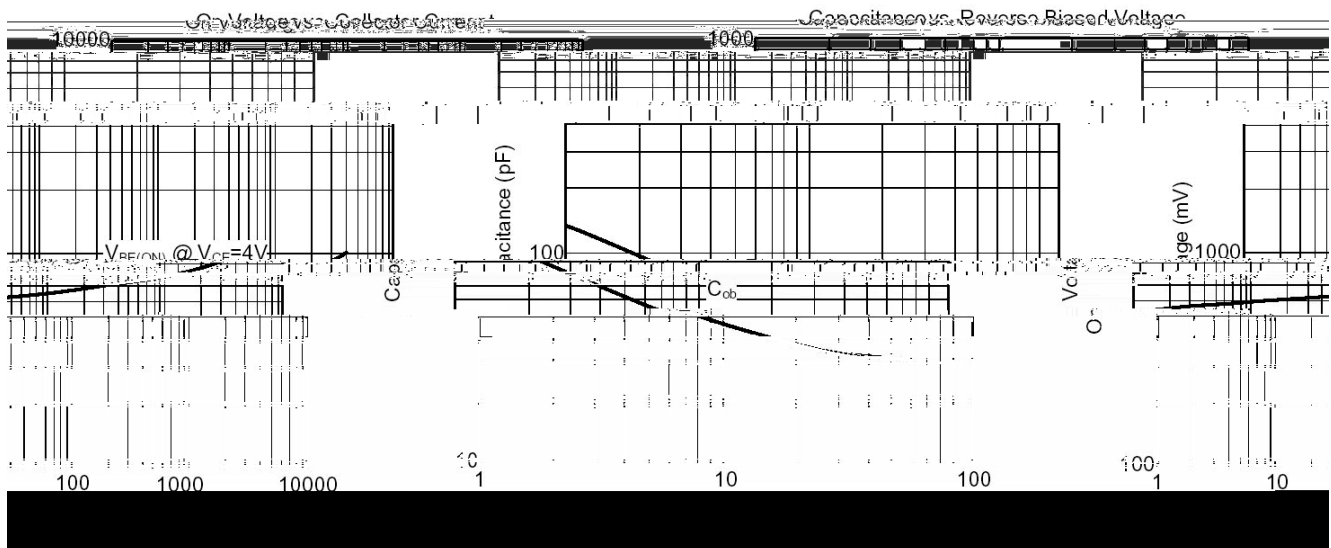
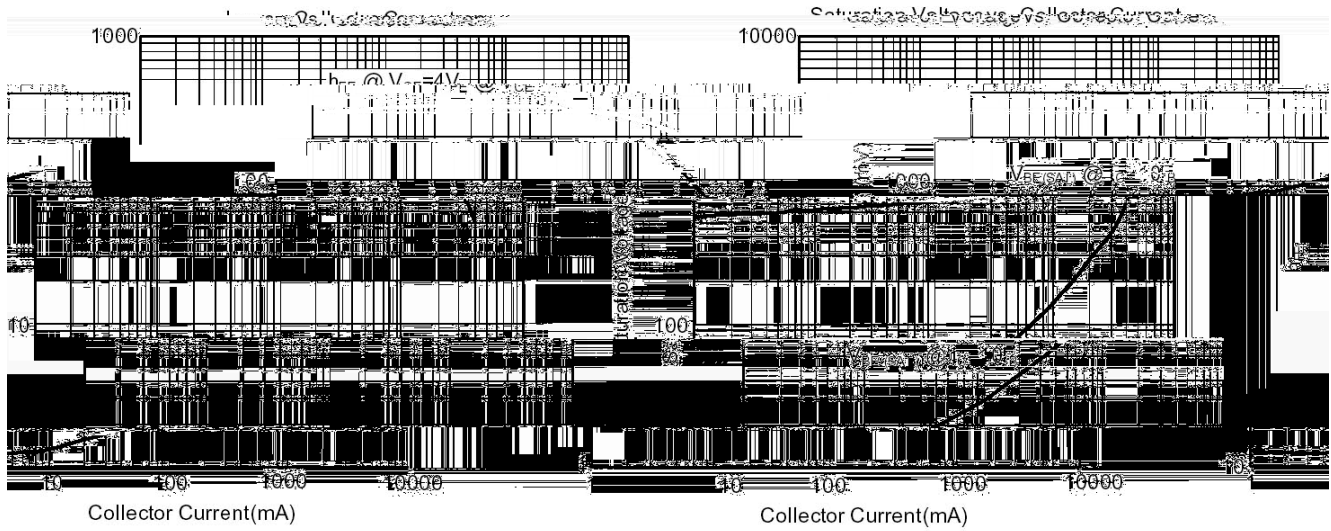
Parameter	Symbol	Rating	Unit
Collector to Base Voltage	V_{CBO}	-70	V
Collector to Emitter Voltage	V_{CEO}	-50	V
Emitter to Base Voltage	V_{EBO}	-5.0	V
Collector Current - Continuous	I_C	-4.0	A
Base Current - Continuous	I_{CP}	-8.0	A
Collector Power Dissipation	$P_C(T_C=25^\circ\text{C})$	40	W
Junction Temperature	T_j	150	$^\circ\text{C}$
Storage Temperature Range	T_{stg}	-55 150	$^\circ\text{C}$

/ Electrical Characteristics($T_a=25^\circ\text{C}$)

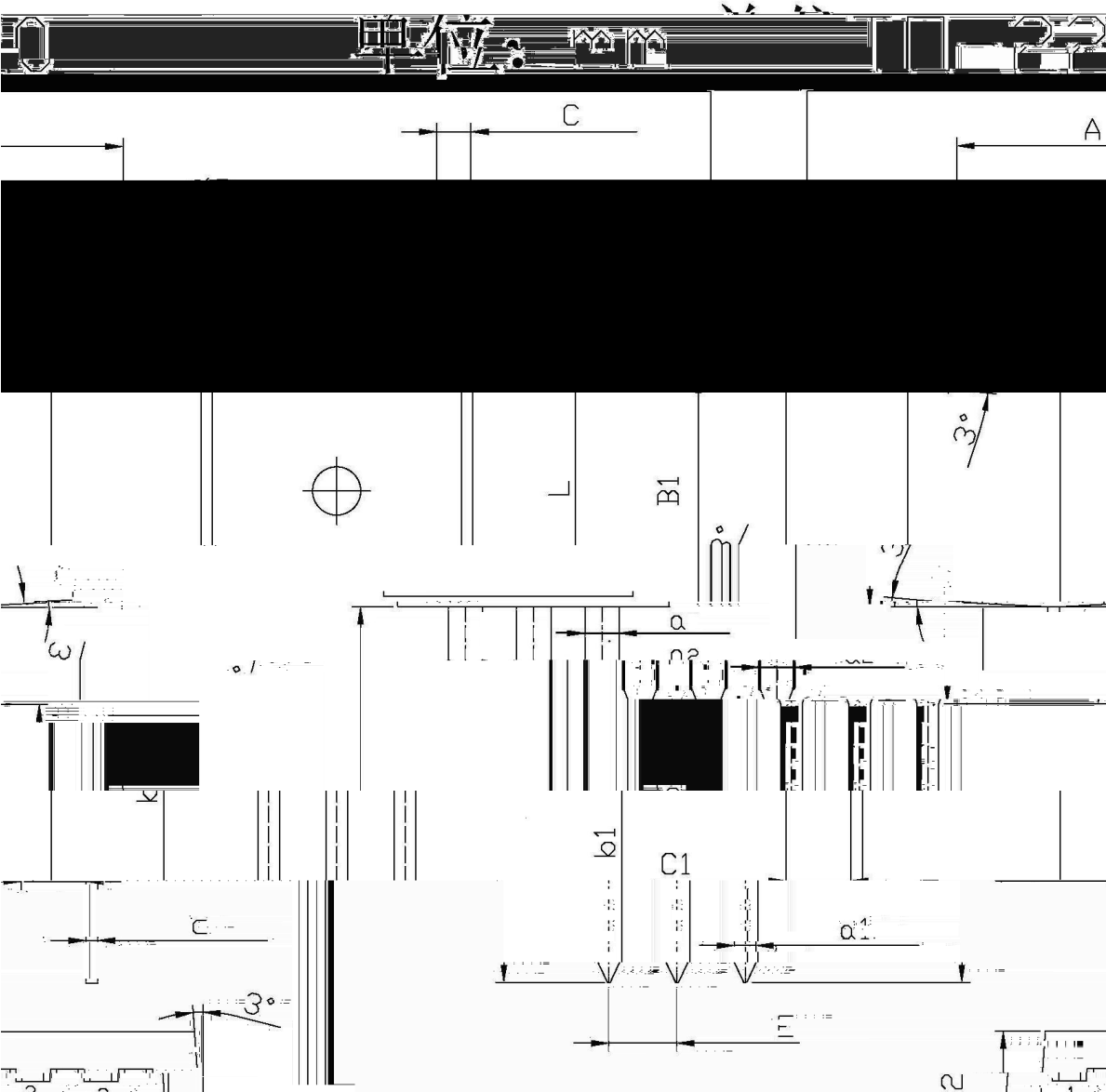
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
Collector to Base Breakdown Voltage	V_{CBO}	$I_C=-10\text{ A}$ $I_E=0$	-70			V
Collector to Emitter Breakdown Voltage	V_{CEO}	$I_C=-50\text{mA}$ $I_B=0$	-50			V
Emitter to Base Breakdown Voltage	V_{EBO}	$I_E=-10\text{ A}$ $I_C=0$	-5.0			V
Collector Cut-Off Current	I_{CBO}	$V_{CB}=-50\text{V}$ $I_E=0$			-1.0	A
DC Current Gain	$h_{FE(1)*}$	$V_{CE}=-4.0\text{V}$ $I_C=-1.0\text{A}^*$	60		320	
	$h_{FE(2)*}$	$V_{CE}=-4.0\text{V}$ $I_C=-0.1\text{A}^*$	35			
Collector to Emitter Saturation Voltage*	$V_{CE(sat)*}$	$I_C=-2.0\text{A}$ $I_B=-0.2\text{A}^*$			-1.0	V
Base to Emitter Voltage*	V_{BE*}	$V_{CE}=-4.0\text{V}$ $I_C=-1.0\text{A}^*$			-1.0	V
Transition Frequency*	f_T^*	$V_{CE}=-4.0\text{V}$ $I_C=-0.5\text{A}^*$		15		MHz

* /Pulse test.

/ Electrical Characteristic Curve

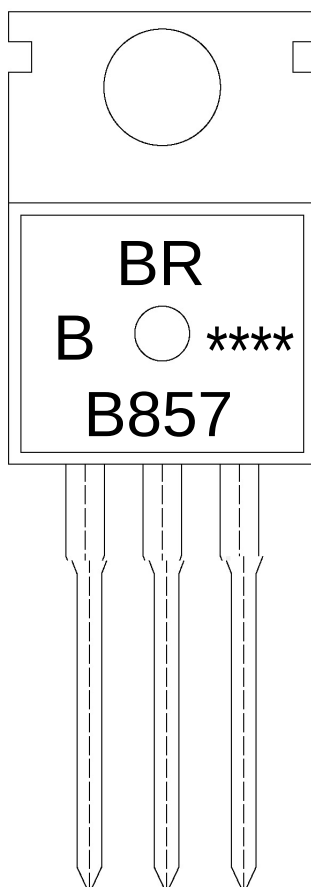


/ Package Dimensions



Symbol	Dimensions in millimeters		Symbol	Dimensions in millimeters		
	Min	Max		Min	Max	
	21.4	21.8		12.4	14.4	
	3.56	3.64		6.3	6.7	
	9.4	9.6		15.7	16.1	
	10.2	10.6		12.4	12.8	

/ Marking Instructions



BR

B857

B: h_{FE}

Note:

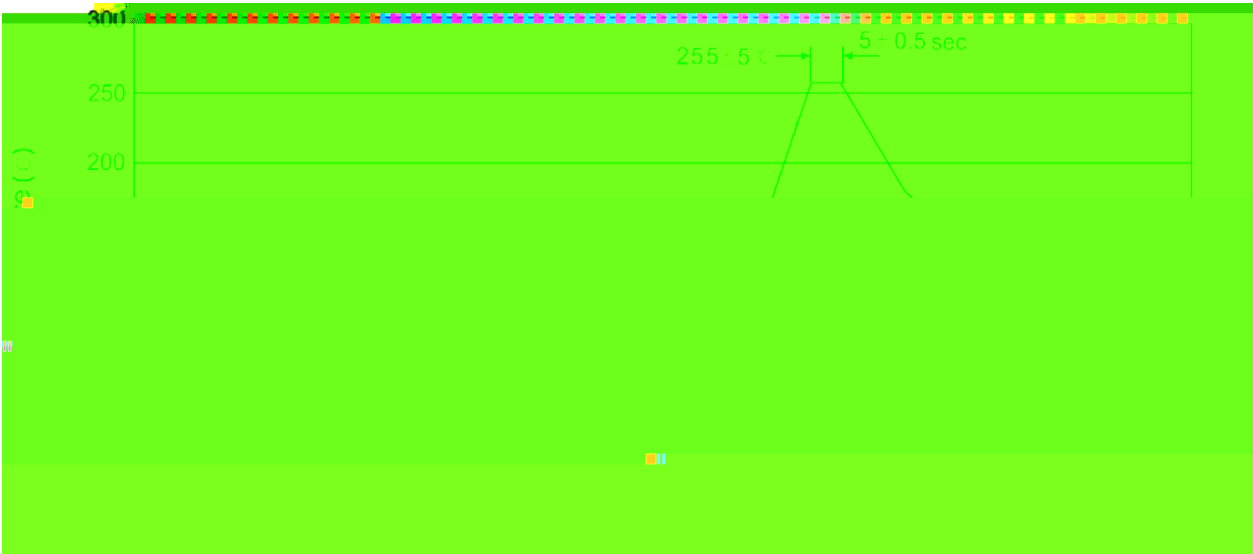
BR: Company Code

B857: Product Type.

B: h_{FE} Classifications Symbol

****: Lot No. Code, code change with Lot No.

() / Temperature Profile for Dip Soldering(Pb-Free)



Note:

- 1

25 150

60 90sec;
- 2

255±5

5±0.5sec;
- 3

2 10

/sec.
- 1.Preheating:25~150

, Time:60~90sec.
- 2.Peak Temp.:255±5

, Duration:5±0.5sec.
3. Cooling Speed: 2~10

/sec.

/ Resistance to Soldering Heat Test Conditions

270±5

10±1 sec.

Temp.:270±5℃

Time:10±1 sec

/ Packaging SPEC.

/ BULK

Package Type 封装形式	Units 包装数量		Dimension 包装尺寸 (unit: mm ³)
	Units/Bag 只/袋	Bags/Inner Box 袋/盒	